



In re Application of:  
Reginald Hunter

**Serial No.: 09/680,226**

**Confirmation No.: 1604**

Filed: October 6, 2000

**For: Method and Apparatus for  
Enhanced Embedded Substrate  
Inspection Through Process  
Data Collection and Substrate  
Imaging Techniques**

**Group Art Unit: 2877**

**Examiner:** Zandra Smith

**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

**CERTIFICATE OF MAILING**  
**37 CFR 1.8**

I hereby certify that this correspondence is being deposited on April 19, 2004, with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

April 19, 2004  
Date

Air Transport  
Signature

**Dear Sir;**

05/26/2004, TIANRENG, DONGYU, FENG, ZHANG

01 FC:1806

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

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